L	Hits	Search Text	DB	Time stamp
Number	11103			
-	2045	438/613.ccls. 438/411.ccls.	USPAT;	2003/05/15
		438/461.ccls. 438/611.ccls.	EPO; JPO	23:10
		257/737.ccls.		
_	956		USPAT;	2003/05/14
		438/461.ccls. 438/611.ccls.	EPO; JPO	21:05
		257/737.ccls.) and bumps		
-	36	((438/613.ccls. 438/411.ccls.	USPAT;	2003/05/14
		438/461.ccls. 438/611.ccls.	EPO; JPO	21:06
		257/737.ccls.) and bumps) and		
		"thermoplastic resin"		
-	4		USPAT;	2003/05/14
		438/461.ccls. 438/611.ccls.	EPO; JPO	21:06
		257/737.ccls.) and bumps) and		
		"thermoplastic resin") and jig		/
-	1377		USPAT;	2003/05/15
		438/461.ccls. 438/611.ccls.	EPO; JPO	18:50
		257/737.ccls. and "flip chip"		0000 405 415
-	680		USPAT;	2003/05/15
		438/461.ccls. 438/611.ccls.	EPO; JPO	18:51
		257/737.ccls. and "flip chip") and bump	1	0000 /05 /15
-	14	((438/613.ccls. 438/411.ccls.	USPAT;	2003/05/15
		438/461.ccls. 438/611.ccls.	EPO; JPO	18:57
1		257/737.ccls. and "flip chip") and		•
	_	bump) and "base substrate"		2002/05/15
-	0	bumps near "pressed in"	USPAT;	2003/05/15
			EPO; JPO	18:59
-	0	"electrically connecting the bumps"	USPAT;	2003/05/15
	255	-1	EPO; JPO	1
-	375	electric\$4 near connect\$3 near bumps	USPAT; EPO; JPO	2003/05/15
	_	/.7		1
-	0	(electric\$4 near connect\$3 near bumps)	USPAT; EPO; JPO	2003/05/15
	20	same ((one single) adj step)	USPAT;	2003/05/15
_	20	(electric\$4 near connect\$3 near bumps)	EPO; JPO	19:10
	2	same (sealing adhering) ("6208525" "5602420").pn.	USPAT	2003/05/15
-	2	(0200323	OSPAI	23:10
	1	(("6208525" "5602420").pn.) and jig	USPAT	2003/05/15
	1	(0200020 0002420).pii.) and jig	OSFAI	23:10
			<u></u>	23.10